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PSiP and PwrSoC Based Opportunities and Solutions for High Power Systems

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Outline

- Case 1: Powering Large Digital Processor ICs
- Case 2: Data Communication Power System
- Conclusion



RUMENTS



Case 1: Powering Large Scale Digital ICs



- Power and Ground Planes provide supply voltage to large digital ICs
- Stray R, L and C of plane determine the voltage and current distribution.
- Existing Voltage Regulators control only one point of plane where the feedback is connected.
- All Power Distribution Area should have equal voltage potential for noise immunity and electromagnetic compatibility of digital system









Note: This concept of powering large digital processors has been initially reported at ITS-2004 in presentation:

"Alternative Approach of Powering VLSI Digital ICs Using Multi-Cell VRM"

The related US Patent 6,646,425 has been awarded in 2003





Multi-Cell Voltage Regulator



To avoid confusion: There is no physical separation of plane areas!



Load Line Regulation

"Load Line" type voltage regulation

- Improves performance and reliability of processor
- Provides wider window for the output voltage transients



Output current



Modified Droop Paralleling Method





Implementation of Cell as Buck Converter

To other cells







Next Integration Step









Design Goals for Dc-Dc Part of Front-End







Facility Power System with 380-V DC Distribution Bus



demanding requirements to Dc-Dc Transformer



Design Goals for High input Dc-Dc Transformer



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The Need for Integration in Power System



There are 8 drivers with safety insulation (10 overall), at least 4 current sensors with safety insulation (7 overall), 5 voltage sensors with safety insulation (6 overall), 6 isolated bias voltages and only 1 or 2 controllers in this power supply.



Some Integration Trends

Integrated Isolated Bias Supply ICs for POL bias and isolation:



Fully isolated drivers with signal and bias isolation in package:



Isolated current, voltage and temperature sensing:





Target Spec for Micro-Magnetics used in PwrSoC



Micro-Inductor:

Size: 0402, 0603, 0805, 1206 Profile: <0.15 mm (without substrate) Inductance: 20 to 200 nH Frequency: 6 up to 100 MHz Efficiency: 80% to 95% Cost: \$0.01 per sq. mm

Micro-Transformer:

Size: 0402, 0603, 0805, 1206 Profile: <0.1 mm (without substrate) Inductance: 100 to 300 nH Frequency: 10 up to 30 MHz Efficiency: 70% to 90% Cost: \$0.01 per sq. mm Power: 0.5 to 1.0W Isolation: up to 3kV rms





Conclusion

- There is strong motivation for PSiP and PwrSoC approach even in high current and power systems
- In Case 1 of powering large scale digital processors, PwrSoC approach allows reduce the number of external decoupling capacitors and improve transient response
- In Case 2 of Data Communication Power System, PwrSoC approach applied to bias supplies, driver ICs and current/voltage sensing allows increase efficiency and power density, reduce time to market



